

Reference Specification

Leaded MLCC for Automotive (Powertrain/Safety) RCE Series

Product specifications in this catalog are as of Feb. 2024, and are subject to change or obsolescence without notice.

Please consult the approval sheet before ordering. Please read rating and Cautions first.

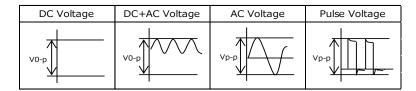
<Reference>Please kindly use our website.

⚠ CAUTION

1. OPERATING VOLTAGE

- 1. Do not apply a voltage to the capacitor that exceeds the rated voltage as called out in the specifications.
 - 1-1. Applied voltage between the terminals of a capacitor shall be less than or equal to the rated voltage.
 - (1) When AC voltage is superimposed on DC voltage, the zero-to-peak voltage shall not exceed the rated DC voltage. When AC voltage or pulse voltage is applied, the peak-to-peak voltage shall not exceed the rated DC voltage.
 - (2) Abnormal voltages (surge voltage, static electricity, pulse voltage, etc.) shall not exceed the rated DC voltage.

Typical Voltage Applied to the DC Capacitor



(E: Maximum possible applied voltage.)

1-2. Influence of over voltage

Over voltage that is applied to the capacitor may result in an electrical short circuit caused by the breakdown of the internal dielectric layers. The time duration until breakdown depends on the applied voltage and the ambient temperature.

2. Use a safety standard certified capacitor in a power supply input circuit (AC filter), as it is also necessary to consider the withstand voltage and impulse withstand voltage defined for each device.

2. OPERATING TEMPERATURE AND SELF-GENERATED HEAT

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself.

When the capacitor is used in a high-frequency current, pulse current or the like, it may have the self-generated heat due to dielectric-loss. In case of Class 2 capacitors (Temp.Char.: X7R,X7S,X8L, etc.), applied voltage should be the load such as self-generated heat is within 20 °C on the condition of atmosphere temperature 25 °C. Please contact us if self-generated heat is occurred with Class 1 capacitors (Temp.Char.: C0G,U2J,X8G, etc.). When measuring, use a thermocouple of small thermal capacity-K of Φ0.1mm and be in the condition where capacitor is not affected by radiant heat of other components and wind of surroundings. Excessive heat may lead to deterioration of the capacitor's characteristics and reliability.

3. FAIL-SAFE

Be sure to provide an appropriate fail-safe function on your product to prevent a second damage that may be caused by the abnormal function or the failure of our product.

4. OPERATING AND STORAGE ENVIRONMENT

The insulating coating of capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. And avoid exposure to moisture. Before cleaning, bonding, or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed 5 to 40 °C and 20 to 70%. Use capacitors within 6 months.

Use capacitors within 6 months after delivered. Check the solderability after 6 months or more.

⚠ CAUTION

5. VIBRATION AND IMPACT

Do not expose a capacitor or its leads to excessive shock or vibration during use.

Excessive shock or vibration may cause to fatigue destruction of lead wires mounted on the circuit board. If necessary, take measures to hold a capacitor on the circuit boards by adhesive, molding resin or coating and other.

Please confirm there is no influence of holding measures on the product with an intended equipment.

6. SOLDERING

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specification of the capacitor. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element.

Please verify that the soldering process does not affect the quality of capacitors.

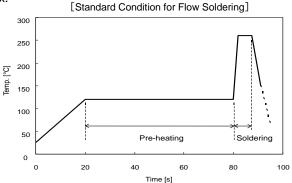
6-1. Flow Soldering

Soldering temperature : 260 °C max.

Soldering time : 7.5 s max.

Preheating temperature : 120 °C max.

Preheating time : 60 s max.



6-2. Reflow Soldering

Do not apply reflow soldering.

6-3. Soldering Iron

Temperature of iron-tip : 350 °C max.
Soldering iron wattage : 60 W max.
Soldering time : 3.5 s max.

7. BONDING AND RESIN MOLDING, RESIN COAT

In case of bonding, molding or coating this product, verify that these processes do not affect the quality of capacitor by testing the performance of a bonded or molded product in the intended equipment. In case of the amount of applications, dryness / hardening conditions of adhesives and molding resins containing organic solvents (ethyl acetate, methyl ethyl ketone, toluene, etc.) are unsuitable, the outer coating resin of a capacitor is damaged by the organic solvents and it may result, worst case, in a short circuit.

The variation in thickness of adhesive or molding resin may cause a outer coating resin cracking and/or ceramic element cracking of a capacitor in a temperature cycling.

8. TREATMENT AFTER BONDING AND RESIN MOLDING, RESIN COAT

When the outer coating is hot (over 100 °C) after soldering, it becomes soft and fragile.

So please be careful not to give it mechanical stress.

Failure to follow the above cautions may result, worst case, in a short circuit and cause fuming or partial dispersion when the product is used.

CAUTION

9. LIMITATION OF APPLICATIONS

The products listed in the specification(hereinafter the product(s) is called as the "Product(s)") are designed and manufactured for applications specified in the specification. (hereinafter called as the "Specific Application")

We shall not warrant anything in connection with the Products including fitness, performance, adequateness, safety, or quality, in the case of applications listed in from (1) to (11) written at the end of this precautions, which may generally require high performance, function, quality, management of production or safety.

Therefore, the Product shall be applied in compliance with the specific application.

WE DISCLAIM ANY LOSS AND DAMAGES ARISING FROM OR IN CONNECTION WITH THE PRODUCTS INCLUDING BUT NOT LIMITED TO THE CASE SUCH LOSS AND DAMAGES CAUSED BY THE UNEXPECTED ACCIDENT, IN EVENT THAT (i) THE PRODUCT IS APPLIED FOR THE PURPOSE WHICH IS NOT SPECIFIED AS THE SPECIFIC APPLICATION FOR THE PRODUCT, AND/OR (ii) THE PRODUCT IS APPLIED FOR ANY FOLLOWING APPLICATION PURPOSES FROM (1) TO (11) (EXCEPT THAT SUCH APPLICATION PURPOSE IS UNAMBIGUOUSLY SPECIFIED AS SPECIFIC APPLICATION FOR THE PRODUCT IN OUR CATALOG SPECIFICATION FORMS, DATASHEETS, OR OTHER DOCUMENTS OFFICIALLY ISSUED BY US*)

- 1. Aircraft equipment
- 2. Aerospace equipment
- 3. Undersea equipment
- 4. Power plant control equipment
- 5. Medical equipment
- 6. Transportation equipment
- 7. Traffic control equipment
- 8. Disaster prevention/security equipment
- 9. Industrial data-processing equipment
- 10. Combustion/explosion control equipment
- 11. Equipment with complexity and/or required reliability equivalent to the applications listed in the above.

For exploring information of the Products which will be compatible with the particular purpose other than those specified in the specification, please contact our sales offices, distribution agents, or trading companies with which you make a deal, or via our web contact form.

Contact form: https://www.murata.com/contactform

*We may design and manufacture particular Products for applications listed in (1) to (11). Provided that, in such case we shall unambiguously specify such Specific Application in the specification without any exception.

Therefore, any other documents and/or performances, whether exist or non-exist, shall not be deemed as the evidence to imply that we accept the applications listed in (1) to (11).

⚠ CAUTION

NOTICE

1. CLEANING (ULTRASONIC CLEANING)

To perform ultrasonic cleaning, observe the following conditions.

Rinse bath capacity: Output of 20 watts per liter or less.

Rinsing time: 5 min maximum.

Do not vibrate the PCB/PWB directly.

Excessive ultrasonic cleaning may lead to fatigue destruction of the lead wires.

2. SOLDERING AND MOUNTING

Insertion of the Lead Wire

- · When soldering, insert the lead wire into the PCB without mechanically stressing the lead wire.
- Insert the lead wire into the PCB with a distance appropriate to the lead space.

3. CAPACITANCE CHANGE OF CAPACITORS

• Class 2 capacitors (Temp.Char. : X7R,X7S,X8L etc.)

Class 2 capacitors an aging characteristic, whereby the capacitor continually decreases its capacitance slightly if the capacitor leaves for a long time. Moreover, capacitance might change greatly depending on a surrounding temperature or an applied voltage. So, it is not likely to be able to use for the time constant circuit.

Please contact us if you need a detail information.

⚠ NOTE

- 1. Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
- 2. You are requested not to use our product deviating from this product specification.

1. Application

This product specification is applied to Leaded MLCC RCE series.

- 1. Specific applications:
- •Automotive powertrain/safety equipment: Products that can be used for automotive equipment related to running, turning, stopping, safety devices, etc., or equipment whose structure, equipment, and performance are legally required to meet technical standards for safety assurance or environmental protection.
- ·Automotive infotainment/comfort equipment: Products that can be used for automotive equipment such as car navigation systems and car audio systems that do not directly relate to human life and whose structure, equipment, and performance are not specifically required by law to meet technical standards for safety assurance or environmental protection.
- ·Medial Equipment [GHTF A/B/C] except for Implant Equipment: Products suitable for use in medical devices designated under the GHTF international classifications as Class A or Class B (the functions of which are not directly involved in protection of human life or property) or in medical devices other than implants designated under the GHTF international classifications as Class C (the malfunctioning of which is considered to pose a comparatively high risk to the human body).
- 2.Unsuitable Application: Applications listed in "Limitation of applications" in this product specification.

2. Rating

• Part Number Configuration

ex.) RCE E1 H03 2J 473 5 Series Temperature Rated Capacitance Capacitance Dimension Lead Individual Package Characteristics Voltage Tolerance (LxW) Style Specification

• Temperature Characteristics

Code	Temp. Char.	Temp. Range	Temp.coef.	Standard Temp.	Operating Temp. Range
71.1	U2J	-55∼25°C	-750+120/-347ppm/°C	25°C	-55 ∼ 125°C
/ 0	(EIA code)	25∼125°C	-750+/-120ppm/°C	25 0	-55.4 125 C

· Rated Voltage

Code	Rated voltage
2E	DC250V
2J	DC630V
3A	DC1000V

Capacitance

The first two digits denote significant figures; the last digit denotes the multiplier of 10 in pF. ex.) In case of 473.

$$47 \times 10^3 = 47000 \text{ pF}$$

Capacitance Tolerance

Code	Capacitance Tolerance
J	+/-5%

• Dimension (LxW)

Please refer to [Part number list].

• Lead Style

*Lead wire is "solder coated CP wire".

Code	Lead Style	Lead spacing (mm)
B1	Straight type	5.0+/-0.8
E1	Straight taping type	5.0+0.6/-0.2
K1	Inside crimp type	5.0+/-0.8
M1	Inside crimp taping type	5.0+0.6/-0.2

• Individual Specification

Murata's control code.

Please refer to [Part number list].

Package

	
Code	Package
Α	Taping type of Ammo
В	Bulk type

3. Marking

Temp. char. : Letter code : U (U2J Char.)

Capacitance : Actual numbers (Less than 100pF)

3 digit numbers (100pF and over)

Capacitance tolerance : Code

Rated voltage : Letter code : 4 (DC250V. Except dimension code : 1)

Letter code : 7 (DC630V) Letter code : A (DC1000V)

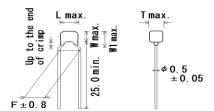
Company name code : Abbreviation : (Except dimension code : 1)

(Ex.)

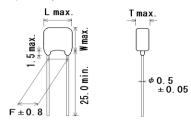
Rated voltage Dimension code	DC250V	DC630V	DC1000V
1	U 102J	_	-
2	(M)103 J4U	€ 472	(M JAU
3,4	_	(103 J7U	G 472 JAU
5	-	473 J7U	(M) 103 JAU

4. Part number list

Inside Crimp (Lead Style:K*)

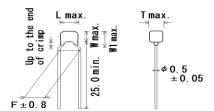


• Straight Long (Lead Style: B1)

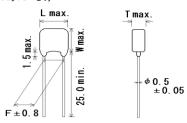


Customer Part Number	Murata Part Number	T.C.	DC Rated Volt.	Сар.	Cap. Tol.		Dime	ension (mm)		Dimension (LxW)	Pack qty.
			(V)			L	W	W1	F	Т	Lead Style	(pcs)
	RCE7U2E101J1K1H03B	U2J	250	100pF	±5%	4.0	3.5	5.0	5.0	3.15	1K1	500
	RCE7U2E151J1K1H03B	U2J	250	150pF	±5%	4.0	3.5	5.0	5.0	3.15	1K1	500
	RCE7U2E221J1K1H03B	U2J	250	220pF	±5%	4.0	3.5	5.0	5.0	3.15	1K1	500
	RCE7U2E331J1K1H03B	U2J	250	330pF	±5%	4.0	3.5	5.0	5.0	3.15	1K1	500
	RCE7U2E471J1K1H03B	U2J	250	470pF	±5%	4.0	3.5	5.0	5.0	3.15	1K1	500
	RCE7U2E681J1K1H03B	U2J	250	680pF	±5%	4.0	3.5	5.0	5.0	3.15	1K1	500
	RCE7U2E102J1K1H03B	U2J	250	1000pF	±5%	4.0	3.5	5.0	5.0	3.15	1K1	500
	RCE7U2E152J1K1H03B	U2J	250	1500pF	±5%	4.0	3.5	5.0	5.0	3.15	1K1	500
	RCE7U2E222J1K1H03B	U2J	250	2200pF	±5%	4.0	3.5	5.0	5.0	3.15	1K1	500
	RCE7U2E332J1K1H03B	U2J	250	3300pF	±5%	4.0	3.5	5.0	5.0	3.15	1K1	500
	RCE7U2E472J1K1H03B	U2J	250	4700pF	±5%	4.0	3.5	5.0	5.0	3.15	1K1	500
	RCE7U2E682J2K1H03B	U2J	250	6800pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2E103J2K1H03B	U2J	250	10000pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J100J2K1H03B	U2J	630	10pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J150J2K1H03B	U2J	630	15pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J220J2K1H03B	U2J	630	22pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J330J2K1H03B	U2J	630	33pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J470J2K1H03B	U2J	630	47pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J680J2K1H03B	U2J	630	68pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J101J2K1H03B	U2J	630	100pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J151J2K1H03B	U2J	630	150pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J221J2K1H03B	U2J	630	220pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J331J2K1H03B	U2J	630	330pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J471J2K1H03B	U2J	630	470pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J681J2K1H03B	U2J	630	680pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J102J2K1H03B	U2J	630	1000pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J152J2K1H03B	U2J	630	1500pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J222J2K1H03B	U2J	630	2200pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J332J2K1H03B	U2J	630	3300pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J472J2K1H03B	U2J	630	4700pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U2J682J3K1H03B	U2J	630	6800pF	±5%	5.5	5.0	7.5	5.0	4.0	3K1	500
	RCE7U2J103J3K1H03B	U2J	630	10000pF	±5%	5.5	5.0	7.5	5.0	4.0	3K1	500
	RCE7U2J153J4K1H03B	U2J	630	15000pF	±5%	7.5	5.5	8.0	5.0	4.0	4K1	500
	RCE7U2J223J4K1H03B	U2J	630	22000pF	±5%	7.5	5.5	8.0	5.0	4.0	4K1	500
	RCE7U2J333J5B1H03B	U2J	630	33000pF	±5%	7.5	8.0	-	5.0	4.0	5B1	500
	RCE7U2J473J5B1H03B	U2J	630	47000pF	±5%	7.5	8.0	-	5.0	4.0	5B1	500
	RCE7U3A100J2K1H03B	U2J	1000	10pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U3A150J2K1H03B	U2J	1000	15pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U3A220J2K1H03B	U2J	1000	22pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U3A330J2K1H03B	U2J	1000	33pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
							-		-			

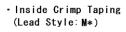
Inside Crimp (Lead Style:K*)

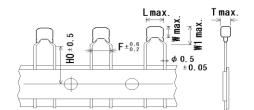


- Straight Long (Lead Style: B1)

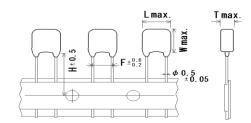


Customer	Murata Part Number	T.C.	DC Rated	Cap.	Сар.		Dime	ension ((mm)		Dimension (LxW)	Pack qty.
Part Number	wurata i art Number	1.0.	Volt. (V)	Сар.	Tol.	L	W	W1	F	Т	Lead Style	
	RCE7U3A470J2K1H03B	U2J	1000	47pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U3A680J2K1H03B	U2J	1000	68pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U3A101J2K1H03B	U2J	1000	100pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U3A151J2K1H03B	U2J	1000	150pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U3A221J2K1H03B	U2J	1000	220pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U3A331J2K1H03B	U2J	1000	330pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U3A471J2K1H03B	U2J	1000	470pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U3A681J2K1H03B	U2J	1000	680pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U3A102J2K1H03B	U2J	1000	1000pF	±5%	5.5	4.0	6.0	5.0	3.15	2K1	500
	RCE7U3A152J3K1H03B	U2J	1000	1500pF	±5%	5.5	5.0	7.5	5.0	4.0	3K1	500
	RCE7U3A222J3K1H03B	U2J	1000	2200pF	±5%	5.5	5.0	7.5	5.0	4.0	3K1	500
	RCE7U3A332J4K1H03B	U2J	1000	3300pF	±5%	7.5	5.5	8.0	5.0	4.0	4K1	500
	RCE7U3A472J4K1H03B	U2J	1000	4700pF	±5%	7.5	5.5	8.0	5.0	4.0	4K1	500
	RCE7U3A682J5B1H03B	U2J	1000	6800pF	±5%	7.5	8.0	-	5.0	4.0	5B1	500
	RCE7U3A103J5B1H03B	U2J	1000	10000pF	±5%	7.5	8.0	-	5.0	4.0	5B1	500





Straight Taping (Lead Style:E*)

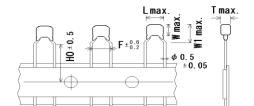


Unit: mm

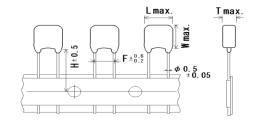
Customer	Murata Part Number	T.C.	DC Rated	Cap.	Cap.	Dimension (mm)						Dimension (LxW)	Pack qty.
Part Number	Warata Fart Namber	1.0.	Volt. (V)	оцр.	Tol.	L	W	W1	F	Т	H/H0	Lead Style	(pcs)
	RCE7U2E101J1M1H03A	U2J	250	100pF	±5%	4.0	3.5	5.0	5.0	3.15	16.0	1M1	2000
	RCE7U2E151J1M1H03A	U2J	250	150pF	±5%	4.0	3.5	5.0	5.0	3.15	16.0	1M1	2000
	RCE7U2E221J1M1H03A	U2J	250	220pF	±5%	4.0	3.5	5.0	5.0	3.15	16.0	1M1	2000
	RCE7U2E331J1M1H03A	U2J	250	330pF	±5%	4.0	3.5	5.0	5.0	3.15	16.0	1M1	2000
	RCE7U2E471J1M1H03A	U2J	250	470pF	±5%	4.0	3.5	5.0	5.0	3.15	16.0	1M1	2000
	RCE7U2E681J1M1H03A	U2J	250	680pF	±5%	4.0	3.5	5.0	5.0	3.15	16.0	1M1	2000
	RCE7U2E102J1M1H03A	U2J	250	1000pF	±5%	4.0	3.5	5.0	5.0	3.15	16.0	1M1	2000
	RCE7U2E152J1M1H03A	U2J	250	1500pF	±5%	4.0	3.5	5.0	5.0	3.15	16.0	1M1	2000
	RCE7U2E222J1M1H03A	U2J	250	2200pF	±5%	4.0	3.5	5.0	5.0	3.15	16.0	1M1	2000
	RCE7U2E332J1M1H03A	U2J	250	3300pF	±5%	4.0	3.5	5.0	5.0	3.15	16.0	1M1	2000
	RCE7U2E472J1M1H03A	U2J	250	4700pF	±5%	4.0	3.5	5.0	5.0	3.15	16.0	1M1	2000
	RCE7U2E682J2M1H03A	U2J	250	6800pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2E103J2M1H03A	U2J	250	10000pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J100J2M1H03A	U2J	630	10pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J150J2M1H03A	U2J	630	15pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J220J2M1H03A	U2J	630	22pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J330J2M1H03A	U2J	630	33pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J470J2M1H03A	U2J	630	47pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J680J2M1H03A	U2J	630	68pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J101J2M1H03A	U2J	630	100pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J151J2M1H03A	U2J	630	150pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J221J2M1H03A	U2J	630	220pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J331J2M1H03A	U2J	630	330pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J471J2M1H03A	U2J	630	470pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J681J2M1H03A	U2J	630	680pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J102J2M1H03A	U2J	630	1000pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J152J2M1H03A	U2J	630	1500pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J222J2M1H03A	U2J	630	2200pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J332J2M1H03A	U2J	630	3300pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J472J2M1H03A	U2J	630	4700pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U2J682J3M1H03A	U2J	630	6800pF	±5%	5.5	5.0	7.5	5.0	4.0	16.0	3M1	2000
	RCE7U2J103J3M1H03A	U2J	630	10000pF	±5%	5.5	5.0	7.5	5.0	4.0	16.0	3M1	2000
	RCE7U2J153J4M1H03A	U2J	630	15000pF	±5%	7.5	5.5	8.0	5.0	4.0	16.0	4M1	1500
	RCE7U2J223J4M1H03A	U2J	630	22000pF	±5%	7.5	5.5	8.0	5.0	4.0	16.0	4M1	1500
	RCE7U2J333J5E1H03A	U2J	630	33000pF	±5%	7.5	8.0	-	5.0	4.0	17.5	5E1	1500
	RCE7U2J473J5E1H03A	U2J	630	47000pF	±5%	7.5	8.0	-	5.0	4.0	17.5	5E1	1500
	RCE7U3A100J2M1H03A	U2J	1000	10pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U3A150J2M1H03A	U2J	1000	15pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U3A220J2M1H03A	U2J	1000	22pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U3A330J2M1H03A	U2J	1000	33pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000

PNLIST

 Inside Crimp Taping (Lead Style: M*)



Straight Taping (Lead Style:E*)



Customer	Murata Part Number	T.C.	DC Rated	Cap.	Cap.		D	imensi	on (mn	n)		Dimension (LxW)	
Part Number	iviulata i art ivumbei	2.0	Volt. (V)	Сар.	Tol.	L	W	W1	F	Т	H/H0	Lead Style	qty. (pcs)
	RCE7U3A470J2M1H03A	U2J	1000	47pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U3A680J2M1H03A	U2J	1000	68pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U3A101J2M1H03A	U2J	1000	100pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U3A151J2M1H03A	U2J	1000	150pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U3A221J2M1H03A	U2J	1000	220pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U3A331J2M1H03A	U2J	1000	330pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U3A471J2M1H03A	U2J	1000	470pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U3A681J2M1H03A	U2J	1000	680pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U3A102J2M1H03A	U2J	1000	1000pF	±5%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	2000
	RCE7U3A152J3M1H03A	U2J	1000	1500pF	±5%	5.5	5.0	7.5	5.0	4.0	16.0	3M1	2000
	RCE7U3A222J3M1H03A	U2J	1000	2200pF	±5%	5.5	5.0	7.5	5.0	4.0	16.0	3M1	2000
	RCE7U3A332J4M1H03A	U2J	1000	3300pF	±5%	7.5	5.5	8.0	5.0	4.0	16.0	4M1	1500
	RCE7U3A472J4M1H03A	U2J	1000	4700pF	±5%	7.5	5.5	8.0	5.0	4.0	16.0	4M1	1500
	RCE7U3A682J5E1H03A	U2J	1000	6800pF	±5%	7.5	8.0	-	5.0	4.0	17.5	5E1	1500
	RCE7U3A103J5E1H03A	U2J	1000	10000pF	±5%	7.5	8.0	-	5.0	4.0	17.5	5E1	1500

Reference only

. Sped No.	cification			
NO.		t Item	Charification	Took Mathed (Compliant Claydord, AEC 0200)
-	Pre-and Post-		Specification	Test Method (Compliant Standard:AEC-Q200)
	Electrical Test			•
	High	Appearance	No defects or abnormalities.	Sit the capacitor for 1000±12h at 150±3°C. Let sit for 24±2h at
	Temperature	Capacitance	Within ±3% or ±0.3pF	*room condition, then measure.
	Exposure	Change	(Whichever is larger)	, and the second
	(Storage)	Q	$30pF \le C : Q \ge 350$	
	(Oto.ugo)		$10pF \le C < 30pF : Q \ge 275+5C/2$	
			10pF > C : Q ≧ 200+10C	
			10p1 > 0 : Q = 2001100	
			C : Nominal Capacitance (pF)	
		I.R.	More than 1,000MΩ or 50 MΩ·μF	
			(Whichever is smaller)	
3	Temperature	Appearance	No defects or abnormalities.	Perform the 1000 cycles according to the four heat treatments listed in
	Cycling	Capacitance	Within ±5% or ±0.5pF	the following table. Let sit for 24±2 h at *room condition, then measure.
	Cyoling .	Change	(Whichever is larger)	and following table. Lot of for 2 122 if at 100 in outside, their modelate.
		Q	$30pF \le C : Q \ge 350$	Step 1 2 3 4
		~	$10pF \le C < 30pF : Q \ge 275+5C/2$	Temp Room Room
			10pF > C : Q ≥ 200+10C	(°C) -55+0/-3 Temp. 125+3/-0 Temp.
			10p1 > 0 : Q = 2001100	Time
			C : Nominal Capacitance (pF)	(min.) 15±3 1 15±3 1
		I.R.	1,000MΩ or 50MΩ·μF min.	
			(Whichever is smaller)	
4	Moisture	Appearance	No defects or abnormalities	Apply the 24h heat (25 to 65°C) and humidity (80 to 98%)
	Resistance	Capacitance	Within ±5% or ± 0.5pF	treatment shown below, 10 consecutive times.
		Change	(Whichever is larger)	Let sit for 24±2 h at *room condition, then measure.
		Q	$30pF \le C : Q \ge 200$	Temperature Humidity Humidity
			30pF > C : Q ≧ 100+10C/3	Humidity 80~98% Humidity 80~98% Humidity
				⁷⁰
			C : Nominal Capacitance (pF)	65 60
		I.R.	500MΩ or 25MΩ•μF min.	55
			(Whichever is smaller)	<u>@</u> 50
			(950 840 840 635
				840 E35
				30 // // // // // // // // // // // // //
				25 +10
				200
				15 10 Initial measurement
				5
				0
				-5
				One cycle 24 hours
				0 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24
				Hours
5	Biased	Appearance	No defects or abnormalities	Apply the rated voltage and DC1 3+0 2/-0V (add 100k 0 resistor)
-	Biased Humidity	Appearance Capacitance	No defects or abnormalities Within +5% or + 0.5pF	Apply the rated voltage and DC1.3+0.2/-0V (add 100k Ω resistor) at 85+3°C and 80 to 85% humidity for 1000+12h
-	Biased Humidity	Capacitance	Within ±5% or ± 0.5pF	at 85±3°C and 80 to 85% humidity for 1000±12h.
-		Capacitance Change	Within ±5% or ± 0.5pF (Whichever is larger)	at 85±3°C and 80 to 85% humidity for 1000±12h. Remove and let sit for 24±2 h at *room condition, then measure.
-		Capacitance	Within $\pm 5\%$ or ± 0.5 pF (Whichever is larger) 30 pF $\leq C : Q \geq 200$	at 85±3°C and 80 to 85% humidity for 1000±12h.
-		Capacitance Change	Within ±5% or ± 0.5pF (Whichever is larger)	at 85±3°C and 80 to 85% humidity for 1000±12h. Remove and let sit for 24±2 h at *room condition, then measure.
-		Capacitance Change	Within $\pm 5\%$ or ± 0.5 pF (Whichever is larger) 30 pF $\leq C: Q \geq 200$ 30 pF > $C: Q \geq 100+10$ C/3	at 85±3°C and 80 to 85% humidity for 1000±12h. Remove and let sit for 24±2 h at *room condition, then measure.
-		Capacitance Change Q	Within $\pm 5\%$ or ± 0.5 pF (Whichever is larger) 30 pF \leq C : Q \geq 200 30 pF > C : Q \geq 100+10C/3 C : Nominal Capacitance (pF)	at 85±3°C and 80 to 85% humidity for 1000±12h. Remove and let sit for 24±2 h at *room condition, then measure.
		Capacitance Change	Within $\pm 5\%$ or ± 0.5 pF (Whichever is larger) 30 pF $\leq C: Q \geq 200$ 30 pF > $C: Q \geq 100+10$ C/3	at 85±3°C and 80 to 85% humidity for 1000±12h. Remove and let sit for 24±2 h at *room condition, then measure.

Reference only

No.	Tes	t Item	Specification	Test Method (Compliant Standard:AEC-Q200)
6	Operational	Appearance	No defects or abnormalities.	Apply voltage in Table for 1000±12h at 125±3°C.
ŭ	Life	Capacitance	Within ±3% or ±0.3pF	Let sit for 24±2 h at *room condition, then measure.
	Liio	Change	(Whichever is larger)	The charge/discharge current is less than 50mA.
		Q	$30pF \le C : Q \ge 350$	The sharge/alcoharge same in 10 loos thair com/ t.
		^Q		Rated Voltage Test Voltage
			$10pF \le C < 30pF : Q \ge 275+5C/2$	DC250V 150% of the rated voltage
			10pF > C : Q ≧ 200+10C	DC630V
			0 11 1 10 11 15	DC1000V 120% of the rated voltage
			C : Nominal Capacitance (pF)	
		I.R.	1,000MΩ or 50MΩ•μF min.	
			(Whichever is smaller)	
7	External Visua		No defects or abnormalities.	Visual inspection.
8	Physical Dime	nsion	Within the specified dimensions.	Using calipers and micrometers.
9	Marking	•	To be easily legible.	Visual inspection.
10	Resistance	Appearance	No defects or abnormalities.	Per MIL-STD-202 Method 215
	to Solvents	Capacitance	Within the specified tolerance.	Solvent 1 : 1 part (by volume) of isopropyl alcohol
		Q	30pF ≦ C : Q ≧ 1,000	3 parts (by volume) of mineral spirits
			30pF > C : Q ≧ 400+20C	Solvent 2 : Terpene defluxer
				Solvent 3: 42 parts (by volume) of water
			C : Nominal Capacitance (pF)	1 part (by volume) of propylene glycol
		I.R.	More than 10,000MΩ or 500 MΩ·μF	monomethyl ether
			(Whichever is smaller)	1 part (by volume) of monoethanolamine
11	Mechanical	Appearance	No defects or abnormalities.	Three shocks in each direction should be applied along 3
	Shock	Capacitance	Within the specified tolerance.	mutually perpendicular axes of the test specimen (18 shocks).
		Q	30pF ≦ C : Q ≧ 1,000	The specified test pulse should be Half-sine and should have a
			$30pF > C : Q \ge 400+20C$	duration: 0.5ms, peak value: 1500G and velocity change: 4.7m/s.
			C : Nominal Capacitance (pF)	
12	Vibration	Appearance	No defects or abnormalities.	The capacitor should be subjected to a simple harmonic motion
	Vibration	Capacitance	Within the specified tolerance.	having a total amplitude of 1.5mm, the frequency being varied
		Q	$30pF \le C : Q \ge 1,000$	uniformly between the approximate limits of 10 and 2,000Hz.
		l G	30pF > C : Q ≥ 400+20C	The frequency range, from 10 to 2000Hz and return to 10Hz,
			30pr > C . Q ≦ 400+20C	1 · · · · · · · · ·
			O . Naminal Caracitana (a.F.)	should be traversed in approximately 20 min. This motion
			C : Nominal Capacitance (pF)	should be applied for 12 items in each 3 mutually perpendicular
10.1	D		N. 16 () 10 ()	directions (total of 36 times).
13-1	Resistance	Appearance	No defects or abnormalities.	The lead wires should be immersed in the melted solder 1.5 to 2.0mm
	to	Capacitance	Within ±2.5% or ±0.25pF	from the root of terminal at 260±5°C for 10±1 seconds.
	Soldering	Change	(Whichever is larger)	• Post-treatment
	Heat	Dielectric	No defects	Capacitor should be stored for 24±2 hours at *room condition.
	(Non-	Strength		
	Preheat)	(Between		
		terminals)	 	
13-2	Resistance	Appearance	No defects or abnormalities.	First the capacitor should be stored at 120+0/-5°C for 60+0/-5 seconds.
	to	Congoitance	Within ±2.5% or ±0.25pF	
		Capacitance	· ·	Then, the lead wires should be immersed in the melted solder 1.5 to
	Soldering	Change	(Whichever is larger)	Then, the lead wires should be immersed in the melted solder 1.5 to 2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds.
	Heat	1 '	· ·	
	· ·	Change	(Whichever is larger)	
	Heat	Change Dielectric	(Whichever is larger)	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds.
	Heat (On- Preheat)	Change Dielectric Strength	(Whichever is larger)	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment
13-3	Heat (On-	Change Dielectric Strength (Between	(Whichever is larger)	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment
13-3	Heat (On- Preheat)	Change Dielectric Strength (Between terminals)	(Whichever is larger) No defects	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition.
13-3	Heat (On- Preheat)	Change Dielectric Strength (Between terminals) Appearance	(Whichever is larger) No defects No defects or abnormalities.	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition
13-3	Heat (On- Preheat) Resistance to	Change Dielectric Strength (Between terminals) Appearance Capacitance	(Whichever is larger) No defects No defects or abnormalities. Within ±2.5% or ±0.25pF	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C
13-3	Heat (On- Preheat) Resistance to Soldering	Change Dielectric Strength (Between terminals) Appearance Capacitance Change	(Whichever is larger) No defects No defects or abnormalities. Within ±2.5% or ±0.25pF (Whichever is larger)	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C Soldering time: 3.5±0.5 seconds
13-3	Heat (On- Preheat) Resistance to Soldering Heat	Change Dielectric Strength (Between terminals) Appearance Capacitance Change Dielectric	(Whichever is larger) No defects No defects or abnormalities. Within ±2.5% or ±0.25pF (Whichever is larger)	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C Soldering time: 3.5±0.5 seconds Soldering position
13-3	Heat (On- Preheat) Resistance to Soldering Heat (soldering	Change Dielectric Strength (Between terminals) Appearance Capacitance Change Dielectric Strength	(Whichever is larger) No defects No defects or abnormalities. Within ±2.5% or ±0.25pF (Whichever is larger)	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C Soldering time: 3.5±0.5 seconds Soldering position Straight Lead: 1.5 to 2.0mm from the root of terminal.
13-3	Heat (On- Preheat) Resistance to Soldering Heat (soldering	Change Dielectric Strength (Between terminals) Appearance Capacitance Change Dielectric Strength (Between	(Whichever is larger) No defects No defects or abnormalities. Within ±2.5% or ±0.25pF (Whichever is larger)	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C Soldering time: 3.5±0.5 seconds Soldering position Straight Lead: 1.5 to 2.0mm from the root of terminal.
13-3	Heat (On- Preheat) Resistance to Soldering Heat (soldering	Change Dielectric Strength (Between terminals) Appearance Capacitance Change Dielectric Strength (Between	(Whichever is larger) No defects No defects or abnormalities. Within ±2.5% or ±0.25pF (Whichever is larger)	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C Soldering time: 3.5±0.5 seconds Soldering position Straight Lead: 1.5 to 2.0mm from the root of terminal. Crimp Lead: 1.5 to 2.0mm from the end of lead bend.
13-3	Heat (On- Preheat) Resistance to Soldering Heat (soldering	Change Dielectric Strength (Between terminals) Appearance Capacitance Change Dielectric Strength (Between	(Whichever is larger) No defects No defects or abnormalities. Within ±2.5% or ±0.25pF (Whichever is larger)	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C Soldering time: 3.5±0.5 seconds Soldering position Straight Lead: 1.5 to 2.0mm from the root of terminal. Crimp Lead: 1.5 to 2.0mm from the end of lead bend. • Post-treatment
	Heat (On- Preheat) Resistance to Soldering Heat (soldering iron method)	Change Dielectric Strength (Between terminals) Appearance Capacitance Change Dielectric Strength (Between terminals)	(Whichever is larger) No defects No defects or abnormalities. Within ±2.5% or ±0.25pF (Whichever is larger) No defects	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C Soldering time: 3.5±0.5 seconds Soldering position Straight Lead: 1.5 to 2.0mm from the root of terminal. Crimp Lead: 1.5 to 2.0mm from the end of lead bend. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition.
	Heat (On- Preheat) Resistance to Soldering Heat (soldering iron method)	Change Dielectric Strength (Between terminals) Appearance Capacitance Change Dielectric Strength (Between terminals)	(Whichever is larger) No defects No defects or abnormalities. Within ±2.5% or ±0.25pF (Whichever is larger) No defects No defects Within ±5% or ±0.5pF	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C Soldering time: 3.5±0.5 seconds Soldering position Straight Lead: 1.5 to 2.0mm from the root of terminal. Crimp Lead: 1.5 to 2.0mm from the end of lead bend. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Perform the 300 cycles according to the two heat treatments listed in the following table (Maximum transfer time is 20s.). Let sit for 24±2 h at
	Heat (On- Preheat) Resistance to Soldering Heat (soldering iron method)	Change Dielectric Strength (Between terminals) Appearance Capacitance Change Dielectric Strength (Between terminals) Appearance Capacitance Change	(Whichever is larger) No defects No defects or abnormalities. Within ±2.5% or ±0.25pF (Whichever is larger) No defects No defects or abnormalities. Within ±5% or ±0.5pF (Whichever is larger)	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C Soldering time: 3.5±0.5 seconds Soldering position Straight Lead: 1.5 to 2.0mm from the root of terminal. Crimp Lead: 1.5 to 2.0mm from the end of lead bend. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Perform the 300 cycles according to the two heat treatments listed in the
	Heat (On- Preheat) Resistance to Soldering Heat (soldering iron method)	Change Dielectric Strength (Between terminals) Appearance Capacitance Change Dielectric Strength (Between terminals)	(Whichever is larger) No defects No defects or abnormalities. Within ±2.5% or ±0.25pF (Whichever is larger) No defects No defects No defects or abnormalities. Within ±5% or ±0.5pF (Whichever is larger) 30pF ≤ C : Q ≥ 350	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C Soldering time: 3.5±0.5 seconds Soldering position Straight Lead: 1.5 to 2.0mm from the root of terminal. Crimp Lead: 1.5 to 2.0mm from the end of lead bend. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Perform the 300 cycles according to the two heat treatments listed in the following table (Maximum transfer time is 20s.). Let sit for 24±2 h at
	Heat (On- Preheat) Resistance to Soldering Heat (soldering iron method)	Change Dielectric Strength (Between terminals) Appearance Capacitance Change Dielectric Strength (Between terminals) Appearance Capacitance Change	(Whichever is larger) No defects No defects or abnormalities. Within ±2.5% or ±0.25pF (Whichever is larger) No defects No defects No defects or abnormalities. Within ±5% or ±0.5pF (Whichever is larger) 30pF ≤ C : Q ≥ 350 10pF ≤ C < 30pF : Q ≥ 275+5C/2	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C Soldering time: 3.5±0.5 seconds Soldering position Straight Lead: 1.5 to 2.0mm from the root of terminal. Crimp Lead: 1.5 to 2.0mm from the end of lead bend. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Perform the 300 cycles according to the two heat treatments listed in the following table (Maximum transfer time is 20s.). Let sit for 24±2 h at *room condition, then measure.
	Heat (On- Preheat) Resistance to Soldering Heat (soldering iron method)	Change Dielectric Strength (Between terminals) Appearance Capacitance Change Dielectric Strength (Between terminals) Appearance Capacitance Change	(Whichever is larger) No defects No defects or abnormalities. Within ±2.5% or ±0.25pF (Whichever is larger) No defects No defects No defects or abnormalities. Within ±5% or ±0.5pF (Whichever is larger) 30pF ≤ C : Q ≥ 350	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C Soldering time: 3.5±0.5 seconds Soldering position Straight Lead: 1.5 to 2.0mm from the root of terminal. Crimp Lead: 1.5 to 2.0mm from the end of lead bend. Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Perform the 300 cycles according to the two heat treatments listed in the following table (Maximum transfer time is 20s.). Let sit for 24±2 h at *room condition, then measure.
	Heat (On- Preheat) Resistance to Soldering Heat (soldering iron method)	Change Dielectric Strength (Between terminals) Appearance Capacitance Change Dielectric Strength (Between terminals) Appearance Capacitance Change	No defects or abnormalities. Within ±2.5% or ±0.25pF (Whichever is larger) No defects No defects or abnormalities. Within ±5% or ±0.5pF (Whichever is larger) 30pF ≤ C: Q ≥ 350 10pF ≤ C < 30pF: Q ≥ 275+5C/2 10pF > C: Q ≥ 200+10C	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C Soldering time: 3.5±0.5 seconds Soldering position Straight Lead: 1.5 to 2.0mm from the root of terminal. Crimp Lead: 1.5 to 2.0mm from the end of lead bend. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Perform the 300 cycles according to the two heat treatments listed in the following table (Maximum transfer time is 20s.). Let sit for 24±2 h at *room condition, then measure. Step 1 2 Temp. (°C) -55+0/-3 125+3/-0
	Heat (On- Preheat) Resistance to Soldering Heat (soldering iron method)	Change Dielectric Strength (Between terminals) Appearance Capacitance Change Dielectric Strength (Between terminals) Appearance Capacitance Change Q	(Whichever is larger) No defects No defects or abnormalities. Within ±2.5% or ±0.25pF (Whichever is larger) No defects No defects Within ±5% or ±0.5pF (Whichever is larger) 30pF ≤ C : Q ≥ 350 10pF ≤ C < 30pF : Q ≥ 275+5C/2 10pF > C : Q ≥ 200+10C C : Nominal Capacitance (pF)	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C Soldering time: 3.5±0.5 seconds Soldering position Straight Lead: 1.5 to 2.0mm from the root of terminal. Crimp Lead: 1.5 to 2.0mm from the end of lead bend. Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Perform the 300 cycles according to the two heat treatments listed in the following table (Maximum transfer time is 20s.). Let sit for 24±2 h at *room condition, then measure. Step 1 2 Temp. (°C) -55+0/-3 125+3/-0
	Heat (On- Preheat) Resistance to Soldering Heat (soldering iron method)	Change Dielectric Strength (Between terminals) Appearance Capacitance Change Dielectric Strength (Between terminals) Appearance Capacitance Change	No defects or abnormalities. Within ±2.5% or ±0.25pF (Whichever is larger) No defects No defects or abnormalities. Within ±5% or ±0.5pF (Whichever is larger) 30pF ≤ C: Q ≥ 350 10pF ≤ C < 30pF: Q ≥ 275+5C/2 10pF > C: Q ≥ 200+10C	2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Test condition Temperature of iron-tip: 350±10°C Soldering time: 3.5±0.5 seconds Soldering position Straight Lead: 1.5 to 2.0mm from the root of terminal. Crimp Lead: 1.5 to 2.0mm from the end of lead bend. • Post-treatment Capacitor should be stored for 24±2 hours at *room condition. Perform the 300 cycles according to the two heat treatments listed in the following table (Maximum transfer time is 20s.). Let sit for 24±2 h at *room condition, then measure. Step 1 2 Temp. (°C) -55+0/-3 125+3/-0 Time 15+3 15+3

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Reference only

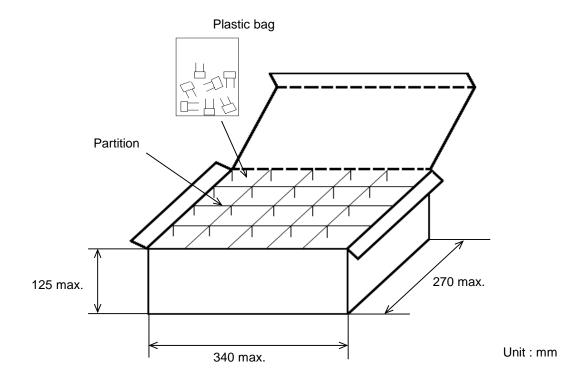
				Referenc	COIN			
No.	Tes	t Item		Specification		Test Method (Compliant Standard:AEC-Q200)		
	Test Item ESD Appearance		No defects or abnormalities.					
15	ESD	Appearance			Per AEC-Q200-002			
		Capacitance	_	specified tolerance.				
		Q	$30pF \le C : Q \ge 1,000$ $30pF > C : Q \ge 400+20C$					
			C : Nomina	C : Nominal Capacitance (pF)				
		I.R.	_	10,000MΩ or 500MΩ•μF				
				(Whichever is smaller)				
4.0	Caldarahilitu	!	,		Chauld ha	a placed into atoms aging for Ob . 45 pain		
16	Solderability		Lead wire should be soldered with uniform			e placed into steam aging for 8h±15 min.		
			coating on the axial direction over 95% of		The terminal of capacitor is dipped into a solution of rosin			
			the circumferential direction.		ethanol (25% rosin in weight propotion).			
					Immerse in solder solution for 2±0.5 seconds.			
					In both cases the depth of dipping is up to about 1.5 to 2mm from the			
					terminal body. Temp. of solder: 245±5°C (Sn-3.0Ag-0.5Cu)			
17	Electrical	Appearance	No defects or abnormalities.		Visual insp	spection.		
l	Characte-	Capacitance	Within the specified tolerance.		The capacitance, Q should be measured at 25°C at the frequency and			
	rization	Q	30pF ≤ C : Q ≥ 1,000		voltage shown in the table.			
	nzation	Q	30pF ≥ C : Q ≥ 1,000 30pF > C : Q ≥ 400+20C		Vollage 311			
			C : Nominal Capacitance (pF)			Nominal Cap. Frequency Voltage		
						$C \le 1000pF$ 1±0.1MHz AC0.5 to 5V(r.m.s.)		
			C . Nomina	і Фарабітапов (рг)		C > 1000pF 1±0.1kHz AC1±0.2V(r.m.s.)		
		<u> </u>	L .	La annua	<u> </u>			
		I.R.	Between	10,000MΩ or 500MΩ•μF min.		ation resistance should be measured with DC500V		
			Terminals	(Whichever is smaller)		in case of rated voltage : DC250V) at 25 °C within 2 min.		
					of chargin	ng.		
		Dielectric	Between Terminals No defects or abnormalities.	No defects or abnormalities.	The capac	citor should not be damaged when voltage in Table is		
		Strength			applied be	etween the terminations for 1 to 5 seconds.		
					(Charge/D	Discharge current ≤ 50mA.)		
					Rated Voltage Test Voltage			
					DC250V 200% of the rated voltage			
						DC630V 150% of the rated voltage		
						DC1000V 130% of the rated voltage		
					DC 1000V 130% of the fated voltage			
			Terminal No defects or abnormalities.		The capacitor is placed in a container with metal balls of 1mm			
			То	no defects of abilitimalities.	diameter so that each terminal, short-circuit is kept approximately			
			External Resin		1			
					n the balls, and 200% of the rated DC voltage (130% of the			
				rated voltage in case of rated voltage: DC630V,DC1000V) is impressed for 1 to 5 seconds between capacitor terminals and metal balls.				
						Discharge current ≤ 50mA.)		
18	Terminal Tensile		Termination not to be broken or loosened.		As in the f	figure, fix the capacitor body, apply the force gradually		
	Strength	Strength			to each lead in the radial direction of the capacitor until reaching 10N and then keep the force applied for 10±1 seconds.			
		Bending	Termination not to be broken or loosened.		Each lead	d wire should be subjected to a force of 2.5N and then		
		Strength				10° at the point of egress in one direction. Each wire is then		
					returned to the original position and bent 90° in the opposite			
		1				at the rate of one bend per 2 to 3 seconds.		
19	Capacitance		Within the specified Tolerance		The capacitance change should be measured after 5min. at			
19					cified temperature step.			
	Temperature Characteristics		25°C to 125°C : -750±120 ppm/°C -55°C to 25°C : -750+120/-347 ppm/°C		caur spec			
						Step Temperature(°C)		
						1 25±2		
						2 -55±3		
						3 25±2 4 125±3		
						5 25±2		
					The temper	The temperature coefficient is determined using the capacitance		
					measured in step 3 as a reference. When cycling the temperature			
					sequential	ally from step 1 through 5 (-55°C to 125°C)		
					the capacitance should be within the specified tolerance for the			
					temperature coefficient and capacitance change as Table A.			
					The capacitance drift is calculated by dividing the differences			
					between the maximum and minimum measured values in the step			
						5 by the capacitance value in step 3.		
* "roo	m condition" T	emperature · 1	5 to 35°C. Re	elative humidity : 45 to 75%, Atmos				
.50	Jonation 1	poracaro . It	, 110		-pero pross			

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6. Packing specification

•Bulk type (Packing style code : B)

The size of packing case and packing way



The number of packing = *1 Packing quantity \times *2 n

*1 : Please refer to [Part number list].

*2 : Standard n = 20 (bag)

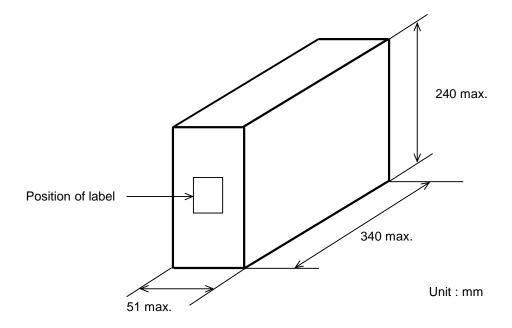
Note)

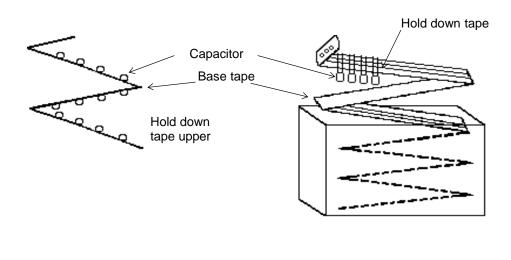
The outer package and the number of outer packing be changed by the order getting amount.

•Ammo pack taping type (Packing style code : A)

A crease is made every 25 pitches, and the tape with capacitors is packed zigzag into a case. When body of the capacitor is piled on other body under it.

The size of packing case and packing way



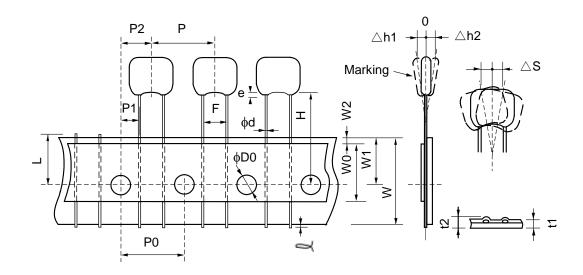


7. Taping specification

7-1. Dimension of capacitors on tape

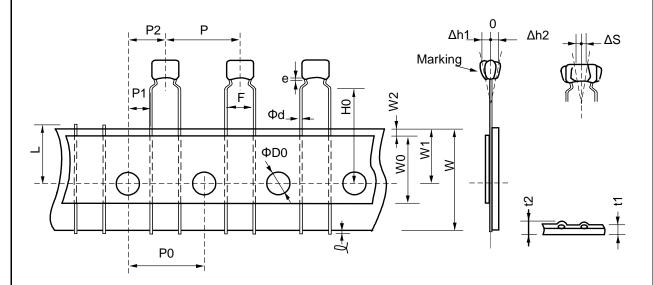
Straight taping type < Lead Style : E1 >

Pitch of component 12.7mm / Lead spacing 5.0mm



Item	Code	Dimensions	Remarks	
Pitch of component	Р	12.7+/-1.0		
Pitch of sprocket hole	P0	12.7+/-0.2		
Lead spacing	F	5.0+0.6/-0.2		
Length from hole center to component center	P2	6.35+/-1.3	Deviation of progress direction	
Length from hole center to lead	P1	3.85+/-0.7		
Deviation along tape, left or right defect	ΔS	0+/-2.0	They include deviation by lead bend	
Carrier tape width	W	18.0+/-0.5		
Position of sprocket hole	W1	9.0+0/-0.5	Deviation of tape width direction	
For straight lead type	Н	17.5+/-0.5		
Protrusion length	l	0.5 max.		
Diameter of sprocket hole	ФD0	4.0+/-0.1		
Lead diameter	Фd	0.5+/-0.05		
Total tape thickness	t1	0.6+/-0.3	They include hold down tape	
Total thickness of tape and lead wire	t2	1.5 max.	thickness.	
Deviation agrees tand	∆h1	2.0 max. (Dimension code : U)		
Deviation across tape	∆h2	1.0 max. (exce	pt as above)	
Portion to cut in case of defect	L	11.0+0/-1.0		
Hold down tape width	W0	9.5 min.		
Hold down tape position	W2	1.5+/-1.5		
Coating extension on lead	е	2.0 max. (Dimension code : U)		
Coating extension on lead		1.5 max. (exce	pt as above)	

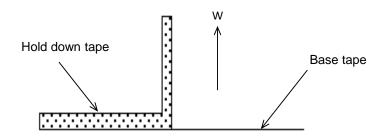
Inside crimp taping type < Lead Style : M1 > Pitch of component 12.7mm / Lead spacing 5.0mm



Item		Dimensions	Remarks	
Pitch of component		12.7+/-1.0		
Pitch of sprocket hole	P0	12.7+/-0.2		
Lead spacing	F	5.0+0.6/-0.2		
Length from hole center to component center	P2	6.35+/-1.3	Deviation of progress direction	
Length from hole center to lead	P1	3.85+/-0.7		
Deviation along tape, left or right defect	ΔS	0+/-2.0	They include deviation by lead bend	
Carrier tape width	W	18.0+/-0.5		
Position of sprocket hole	W1	9.0+0/-0.5	Deviation of tape width direction	
Lead distance between reference and bottom plane	H0	16.0+/-0.5		
Protrusion length	l	0.5 max.		
Diameter of sprocket hole	ФD0	4.0+/-0.1		
Lead diameter	Фd	0.5+/-0.05		
Total tape thickness	t1	0.6+/-0.3	They include hold down tape	
Total thickness of tape and lead wire	t2	1.5 max.	thickness	
Doviation across tapo	∆h1	2.0 max. (Dimension code : W)		
Deviation across tape	Δh2	1.0 max. (ex	ccept as above)	
Portion to cut in case of defect	L	11.0+0/-1.0		
Hold down tape width	W0	9.5 min.		
Hold down tape position	W2	1.5+/-1.5		
Coating extension on lead		Up to the end of crimp		

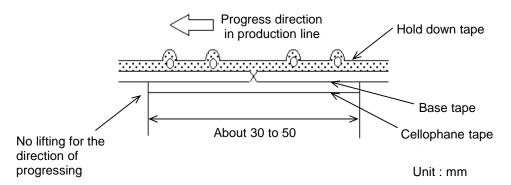
7-2. Splicing way of tape

1) Adhesive force of tape is over 3N at test condition as below.



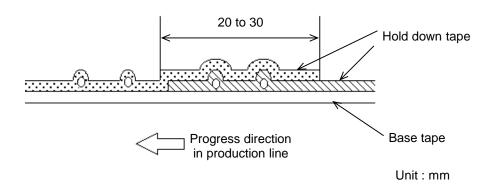
2) Splicing of tape

- a) When base tape is spliced
 - •Base tape shall be spliced by cellophane tape. (Total tape thickness shall be less than 1.05mm.)



b) When hold down tape is spliced

•Hold down tape shall be spliced with overlapping. (Total tape thickness shall be less than 1.05mm.)



- c) When both tape are spliced
 - •Base tape and hold down tape shall be spliced with splicing tape.

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